

Revision:	Date:	Description:	Prepared:	Notes:			
А	9/26/2018	Initial release	JP Digitally signed by JP Date: 2018.09.26 13:52:50 -07'00'	Function test: no open, no short circuit, no		ENSILITY	
			Verified: AG Digitally signed by AG Date: 2018.09.26 13:56:59-0700	intermittent	tel 1.541.323.3228 800 877.670.7118 fax 1.541.323.4202 web tensility.com		
			Dimensions are in				
			millimeters. Tolerances: < 1.0: ± 0.1 mm	<sub>2.2 mm</sub> silver plated, thru hole	Size:	Part number: 54-00129	
			1.0 to 10.0: ± 0.2 mm > 10.0: ± 0.3 mm		Scale:	3:1 Sheet 1 of 2	

5 4 3 2

### Ratings

Maximum operating voltage: 48 V

Maximum operating current: 6.0 A (not mated under load)

#### **Operating Temperature Range**

-25 to 85 °C, relative humidity of 85% or less

#### Materials

1)Insulator: PBT, black

(2)Cover: PBT, black

(3)Terminal: brass, silver plated

(4)Terminal: brass, silver plated

(5) Spring contact: phosphor bronze, silver plated

(6) Center pin: brass, nickel plated

## **Electrical Requirements**

Dielectric strength: 1 min @ 500 Vac

Insulation resistance: 100 MΩ @ 500 Vdc minimum

Contact resistance: 50 mΩ maximum

### **Mechanical Requirements**

Insertion force: 0.3-1.5 kaf

Withdrawal force: 0.3-1.5 kgf

Life cycle: 5000 mating cycles while maintaining contact resistance: 100 m $\Omega$  maximum, insulation resistance: 50 M $\Omega$ 

minimum, withstand voltage: 500 Vac, 1 min

Terminal strength: 300 gf applied to the terminal for 15 seconds in any direction while maintaining electrical characteristics and

without damage or excessive looseness of terminals

### Soldering

Solderability: 75% minimum coverage when terminals dipped 2mm in 245  $\pm$ 5 °C solder bath for 3  $\pm$ 0.5 seconds

Solder bath durability: no deformation when immersed in 255  $\pm$ 5 °C up to surface of the board 1.6 mm for 5 seconds or less

Solder iron durability: no deformation when exposed to 350  $\pm$ 10 °C for 3 ±0.5 seconds

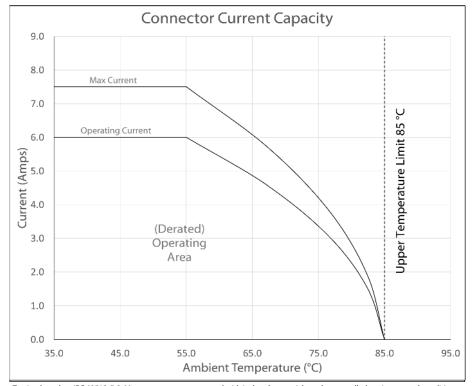
## **Environmental Requirements**

Cold test: -25 ±3 °C for 48 hours without deformation

Heat test: 85 ±2 °C, for 48 hours without deformation

Humidity test: 40 ±2 °C, relative humidity 90-95% for 48 hours

without deformation



Testing based on IEC 60512-5-2. Max current curve generated with isolated test article under controlled environmental conditions, and does not take into account external factors such as housings, mating cables, or other circuitry. Operating current curve (derated by 20% of maximum values) accounts for external factors, and manufacturing variation.

# **Wave Soldering Temperature Profile**

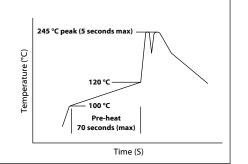
Pb - Free Flow Profile

Solder temperature: 245 °C

Time: 5 seconds maximum

Pre-heat: 100 ~120°C Time: 70 seconds maximum

Measure point: surface of the solder leads



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			Verified:  AG   Digitally signed by AG   Date: 2018:09:26   S35715: 07000   Dimensions are in	intermittent	tel 1.541.323.3228 800 877.670.7118 fax 1.541.323.4202 web tensility.com		
			millimeters.	Description:	Size:	Part number:	
			Tolerances: _ < 1.0: ± 0.1 mm 1.0 to 10.0: ± 0.2 mm > 10.0: ± 0.3 mm	Connector, dc jack 5.5x2.1 mm, PCB mount, 90°, silver plated, thru hole	Α	54-00129	
					Scale:	5:1 Sheet 2 of 2	